

<b>Notice of References Cited</b>	Application/Control No. 09/851,313		Applicant(s)/Patent Under Reexamination USAMI, TATSUYA	
	Examiner JULIO J. MALDONADO		Art Unit 2823	Page 1 of 1

#### U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
*	A	US-6,054,379	04-2000	Yau et al.	438/623
*	B	US-6,333,257	12-2001	Aoi, Nobuo	438/626
*	C	US-6,218,317	04-2001	Allada et al.	438/780
*	D	US-2005/0233591 A1	10-2005	Schmitt et al.	438/706
*	E	US-6,008,540	12-1999	Lu et al.	257/758
	F	US-			
	G	US-			
	H	US-			
	I	US-			
	J	US-			
	K	US-			
	L	US-			
	M	US-			

#### FOREIGN PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N					
	O					
	P					
	Q					
	R					
	S					
	T					

#### NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Chen et al., Effects of Slurry formulations on chemical-mechanical polishing of low dielectric constant polysiloxanes: hydrido-organo siloxane and methyl silsesquioxane; J. Vac. Sci. Technol. B 18(1), Jan/Feb 2000, pages 201-207.
	V	
	W	
	X	

\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
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